



CY62128V Family

128K x 8 Static RAM

Features

- **Low voltage range:**
 - 2.7V–3.6V (CY62128V)
 - 2.3V–2.7V (CY62128V25)
 - 1.6V–2.0V (CY62128V18)
- **Low active power and standby power**
- **Easy memory expansion with CE and OE features**
- **TTL-compatible inputs and outputs**
- **Automatic power-down when deselected**
- **CMOS for optimum speed/power**

Functional Description

The CY62128V family is composed of three high-performance CMOS static RAMs organized as 131,072 words by 8 bits. Easy memory expansion is provided by an active LOW chip enable (\overline{CE}) and active LOW output enable (\overline{OE}) and

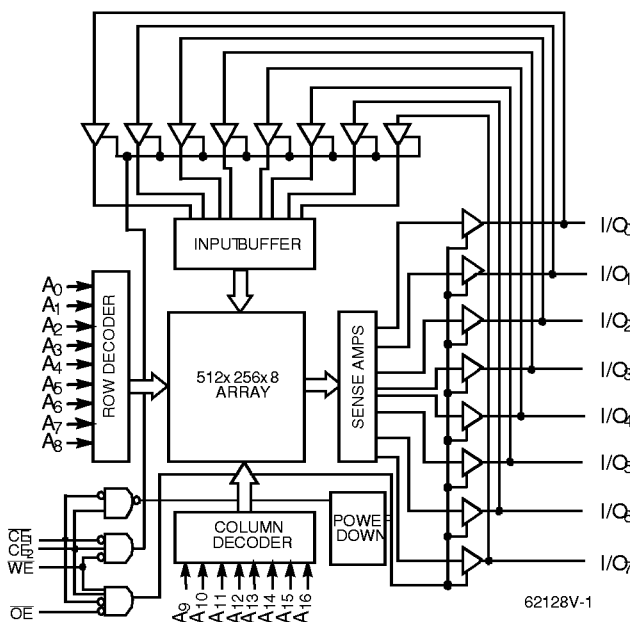
three-state drivers. These devices have an automatic power-down feature, reducing the power consumption by over 99% when deselected. The CY62128V family is available in the standard 450-mil-wide SOIC, TSOP, and STSOP packages.

Writing to the device is accomplished by taking chip enable one (\overline{CE}_1) and write enable (\overline{WE}) inputs LOW and the chip enable two (\overline{CE}_2) input HIGH. Data on the eight I/O pins (I/O_0 through I/O_7) is then written into the location specified on the address pins (A_0 through A_{16}).

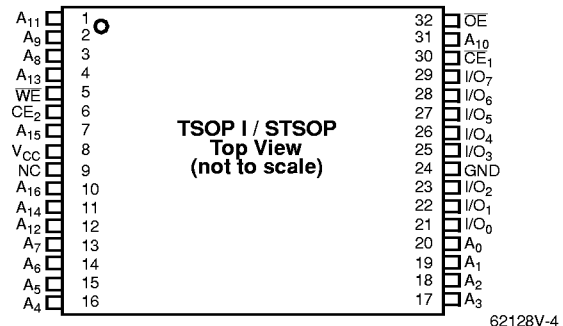
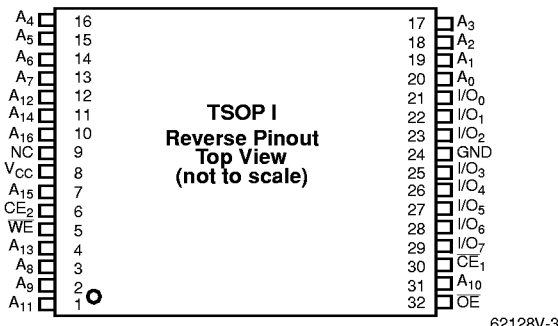
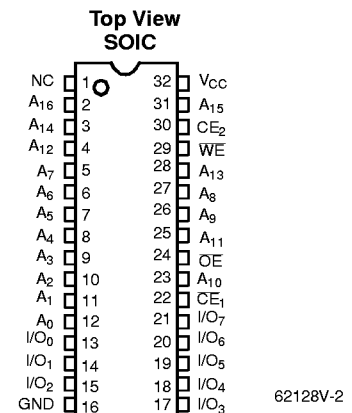
Reading from the device is accomplished by taking chip enable one (\overline{CE}_1) and output enable (\overline{OE}) LOW while forcing write enable (\overline{WE}) and chip enable two (\overline{CE}_2) HIGH. Under these conditions, the contents of the memory location specified by the address pins will appear on the I/O pins.

The eight input/output pins (I/O_0 through I/O_7) are placed in a high-impedance state when the device is deselected (\overline{CE}_1 HIGH or \overline{CE}_2 LOW), the outputs are disabled (\overline{OE} HIGH), or during a write operation (\overline{CE}_1 LOW, \overline{CE}_2 HIGH, and \overline{WE} LOW).

Logic Block Diagram



Pin Configurations





Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

- Storage Temperature -65°C to +150°C
- Ambient Temperature with Power Applied 55°C to +125°C
- Supply Voltage to Ground Potential (Pin 28 to Pin 14) -0.5V to +4.6V
- DC Voltage Applied to Outputs in High Z State^[1] -0.5V to V_{CC} + 0.5V
- DC Input Voltage^[1] -0.5V to V_{CC} + 0.5V

- Output Current into Outputs (LOW) 20 mA
- Static Discharge Voltage >2001V (per MIL-STD-883, Method 3015)
- Latch-Up Current >200 mA

Operating Range

Range	Ambient Temperature	V _{CC}
Commercial	0°C to +70°C	1.6V to 3.6V
Industrial	-40°C to +85°C	1.6V to 3.6V

Product Portfolio

Product	V _{CC} Range			Speed	Power Dissipation (Commercial)			
	Min.	Typ. ^[2]	Max.		Operating (I _{CC})		Standby (I _{SB2})	
					Typ. ^[2]	Maximum	Typ. ^[2]	Maximum
CY62128V	2.7V	3.0V	3.6V	70 ns	20 mA	40 mA	0.4 μA	100 μA (15 μA = LL)
CY62128V25	2.3V	2.5V	2.7V	100 ns	15 mA	20 mA	0.3 μA	50 μA (10 μA = LL)
CY62128V18	1.6V	1.8V	2.0V	200 ns	10 mA	15 mA	0.3 μA	30 μA (10 μA = LL)

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	CY62128V-70			Unit	
			Min.	Typ. ^[2]	Max.		
V _{OH}	Output HIGH Voltage	V _{CC} = Min., I _{OH} = -1.0 mA	2.4			V	
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 2.1 mA			0.4	V	
V _{IH}	Input HIGH Voltage		2		V _{CC} + 0.5V	V	
V _{IL}	Input LOW Voltage		-0.5		0.8	V	
I _{IX}	Input Load Current	GND ≤ V _I ≤ V _{CC}	-1	±1	+1	μA	
I _{OZ}	Output Leakage Current	GND ≤ V _O ≤ V _{CC} , Output Disabled	-1	±1	+1	μA	
I _{CC}	V _{CC} Operating Supply Current	V _{CC} = Max., I _{OUT} = 0 mA, f = f _{MAX} = 1/t _{RC}	Com'l	L	20	40	mA
				LL			
			Ind'l	L			
				LL			
I _{SB1}	Automatic CE Power-Down Current—TTL Inputs	Max. V _{CC} , CE ≥ V _{IH} , V _{IN} ≥ V _{IH} or V _{IN} ≤ V _{IL} , f = f _{MAX}	Com'l	L	15	300	μA
				LL			
			Ind'l	L			
				LL			
I _{SB2}	Automatic CE Power-Down Current—CMOS Inputs	Max. V _{CC} , CE ≥ V _{CC} - 0.3V, V _{IN} ≥ V _{CC} - 0.3V or V _{IN} ≤ 0.3V, f = 0	Com'l	L	0.4	100	μA
				LL		15	μA
			Ind'l	L	100	μA	
				LL	30	μA	

Notes:

1. V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns.
2. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC} Typ, T_A = 25°C.



Electrical Characteristics Over the Operating Range

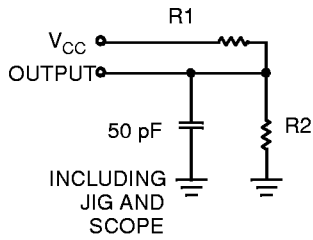
Parameter	Description	Test Conditions	CY62128V25-100			CY62128V18-200			Unit	
			Min.	Typ. ^[2]	Max.	Min.	Typ. ^[2]	Max.		
V _{OH}	Output HIGH Voltage	V _{CC} = Min., I _{OH} = -0.1 mA	2.4			0.8* V _{CC}			V	
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 0.1 mA			0.4			0.2	V	
V _{IH}	Input HIGH Voltage		2		V _{CC} +0.5	0.7* V _{CC}		V _{CC} +0.3	V	
V _{IL}	Input LOW Voltage		-0.5		0.8	-0.5		0.3* V _{CC}	V	
I _{IX}	Input Load Current	GND ≤ V _I ≤ V _{CC}	-1	±1	+1	-1	±0.1	+1	μA	
I _{OZ}	Output Leakage Current	GND ≤ V _O ≤ V _{CC} , Output Disabled	-1	±1	+1	-1	±0.1	+1	μA	
I _{CC}	V _{CC} Operating Supply Current	V _{CC} = Max., I _{OUT} = 0 mA, f = f _{MAX} = 1/t _{RC}	L		15	20		10	15	mA
			LL							
I _{SB1}	Automatic CE Power-Down Current—TTL Inputs	Max. V _{CC} , CE ≥ V _{IH} , V _{IN} ≥ V _{IH} or V _{IN} ≤ V _{IL} , f = f _{MAX}	L		15	300		5	100	μA
			LL							
I _{SB2}	Automatic CE Power-Down Current—CMOS Inputs	Max. V _{CC} , CE ≥ V _{CC} - 0.3V V _{IN} ≥ V _{CC} - 0.3V or V _{IN} ≤ 0.3V, f = 0	L		0.4	50		0.4	30	μA
			LL			12			10	μA
			LL	Indust'l Temp Range		24		20	μA	

Capacitance^[3]

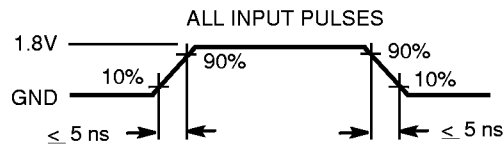
Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	T _A = 25°C, f = 1 MHz, V _{CC} = 3.0V	6	pF
C _{OUT}	Output Capacitance		8	pF

Note:

3. Tested initially and after any design or process changes that may affect these parameters.

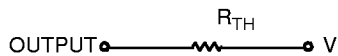
AC Test Loads and Waveforms


62128V-5



62128V-6

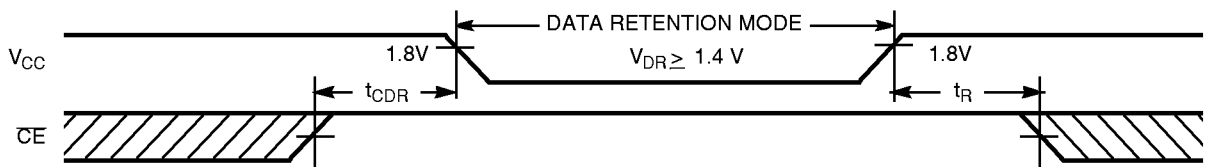
Equivalent to: THÉVENIN EQUIVALENT



Parameters	3.3V	2.5V	1.8V	Unit
R1	1213	15909	10800	Ohms
R2	1378	4487	4154	Ohms
R _{TH}	645	3500	3000	Ohms
V _{TH}	1.75V	0.55V	0.50V	Volts

Data Retention Characteristics (Over the Operating Range)

Parameter	Description		Conditions ^[4]	Min.	Typ. ^[2]	Max.	Unit
V _{DR}	V _{CC} for Data Retention			1.4			V
I _{CCDR}	Data Retention Current	Com'l	L	V _{CC} = 1.6V CE ≥ V _{CC} - 0.3V, V _{IN} ≥ V _{CC} - 0.3V or V _{IN} ≤ 0.3V No input may exceed V _{CC} +0.3V	0.4	10	μA
			LL			10	μA
		Ind'l	L			20	μA
			LL			20	μA
t _{CDR} ^[3]	Chip Deselect to Data Retention Time		0			ns	
t _R	Operation Recovery Time		t _{RC}			ns	

Data Retention Waveform


C62128V-7

Note:

 4. No input may exceed V_{CC}+0.3V.

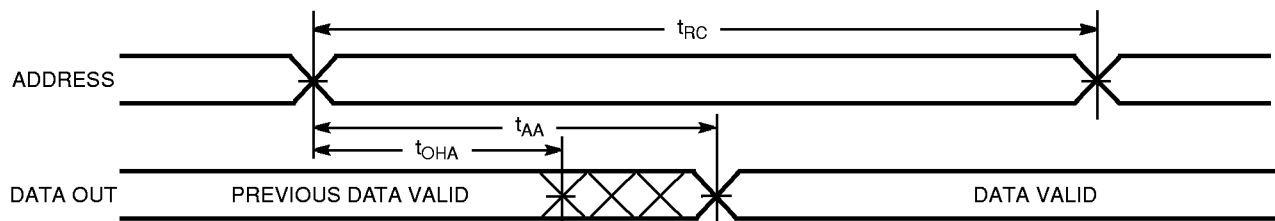


Switching Characteristics Over the Operating Range^[5]

Parameter	Description	CY62128V-70		CY62128V25-100		CY62128V18-200		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
READ CYCLE								
t_{RC}	Read Cycle Time	70		100		200		ns
t_{AA}	Address to Data Valid		70		100		200	ns
t_{OHA}	Data Hold from Address Change	10		10		10		ns
t_{ACE}	\overline{CE} LOW to Data Valid		70		100		200	ns
t_{DOE}	\overline{OE} LOW to Data Valid		35		75		125	ns
t_{LZOE}	\overline{OE} LOW to Low Z ^[6]	10		10		10		ns
t_{HZOE}	\overline{OE} HIGH to High Z ^[6, 7]		25		50		75	ns
t_{LZCE}	\overline{CE} LOW to Low Z ^[6]	10		10		10		ns
t_{HZCE}	\overline{CE} HIGH to High Z ^[6, 7]		25		50		75	ns
t_{PU}	\overline{CE} LOW to Power-Up	0		0		0		ns
t_{PD}	\overline{CE} HIGH to Power-Down		70		100		200	ns
WRITE CYCLE^[8,9]								
t_{WC}	Write Cycle Time	70		100		200		ns
t_{SCE}	\overline{CE} LOW to Write End	60		100		190		ns
t_{AW}	Address Set-Up to Write End	60		100		190		ns
t_{HA}	Address Hold from Write End	0		0		0		ns
t_{SA}	Address Set-Up to Write Start	0		0		0		ns
t_{PWE}	\overline{WE} Pulse Width	55		90		125		ns
t_{SD}	Data Set-Up to Write End	30		60		100		ns
t_{HD}	Data Hold from Write End	0		0		0		ns
t_{HZWE}	\overline{WE} LOW to High Z ^[6, 7]		25		50		100	ns
t_{LZWE}	\overline{WE} HIGH to Low Z ^[6]	5		10		15		ns

Switching Waveforms

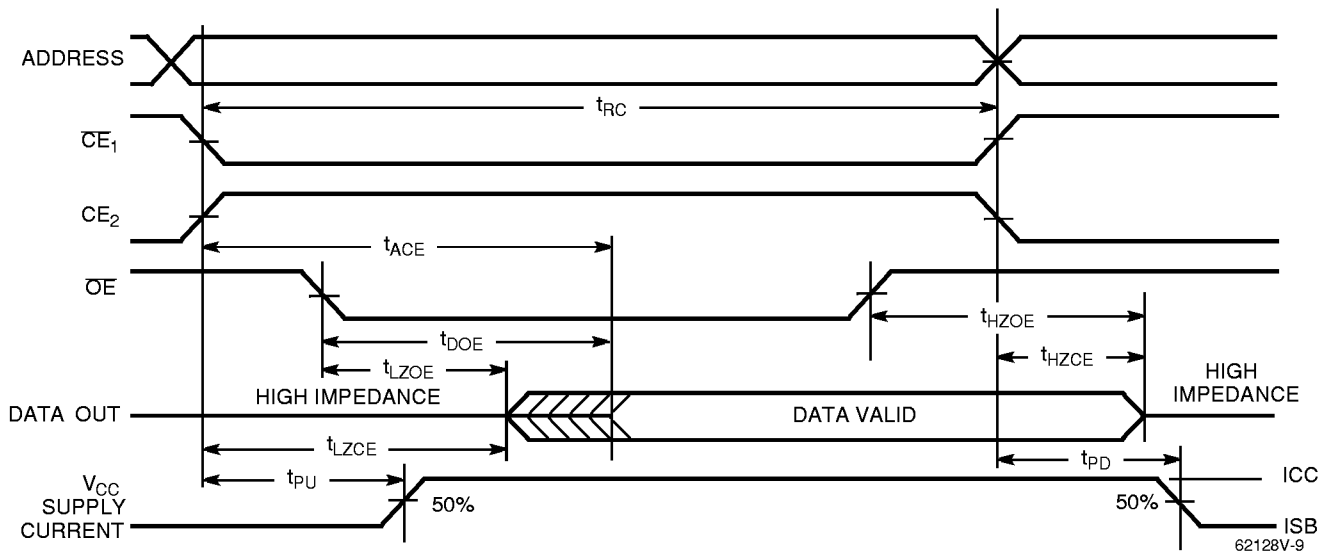
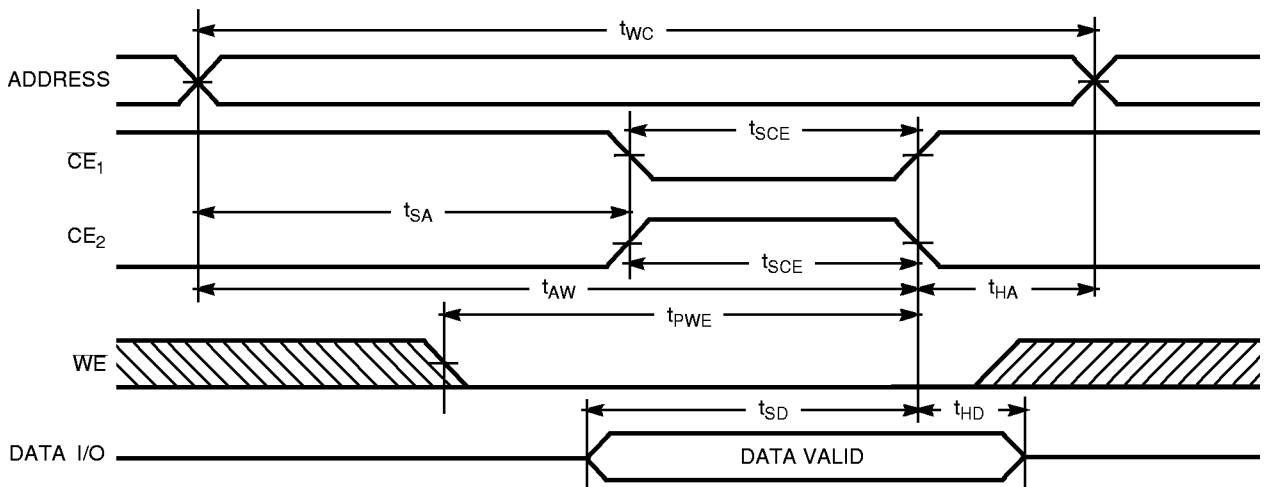
Read Cycle No. 1^[10, 11]



62128V-8

Notes:

- Test conditions assume signal transition time of 5 ns or less timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 100-pF load capacitance.
- At any given temperature and voltage condition, t_{HZOE} is less than t_{LZOE} , t_{HZOE} is less than t_{LZOE} , and t_{HZWE} is less than t_{LZWE} for any given device.
- t_{HZOE} , t_{HZCE} , and t_{HZWE} are specified with $C_L = 5$ pF as in part (b) of AC Test Loads. Transition is measured ± 200 mV from steady-state voltage.
- The internal write time of the memory is defined by the overlap of \overline{CE}_1 LOW, \overline{CE}_2 HIGH and \overline{WE} LOW. \overline{CE}_1 and \overline{WE} signals must be LOW and \overline{CE}_2 HIGH to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
- The minimum write cycle time for write cycle #3 (\overline{WE} controlled, \overline{OE} LOW) is the sum of t_{HZWE} and t_{SD} .
- Device is continuously selected. $\overline{OE}, \overline{CE} = V_{IL}, \overline{CE}_2 = V_{IH}$.
- \overline{WE} is HIGH for read cycle.

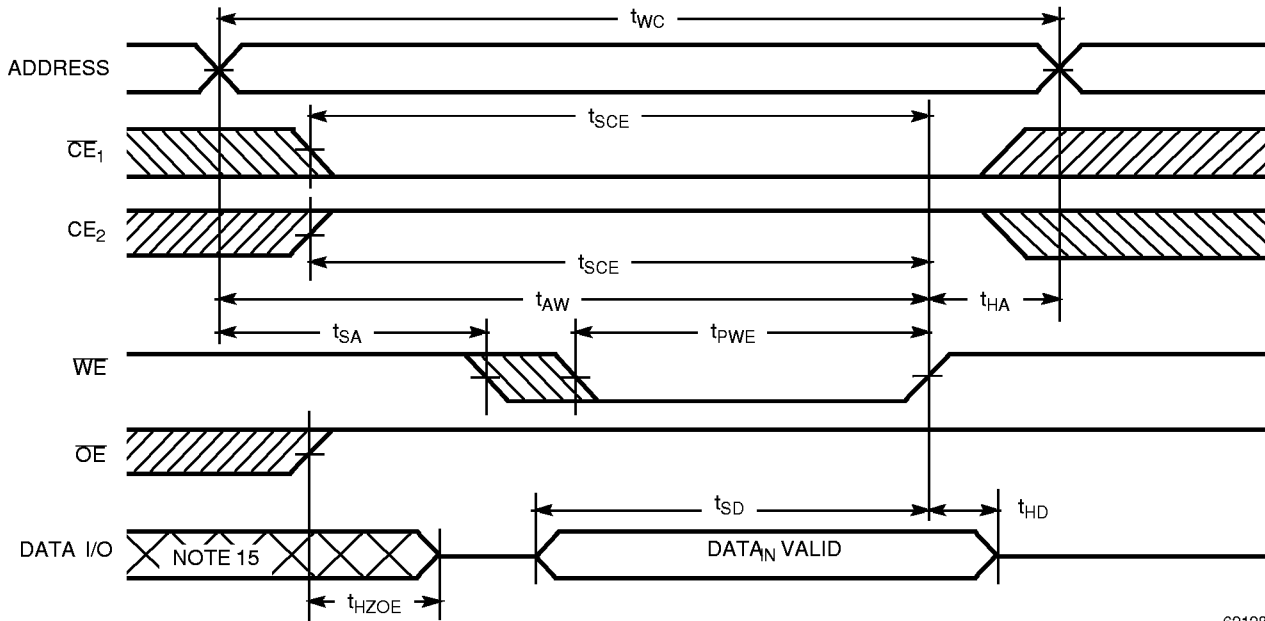
Switching Waveforms (continued)
Read Cycle No. 2 (OE Controlled)^[11,12]

Write Cycle No. 1 (CE₁ or CE₂ Controlled)^[13,14]


62128V-10

Notes:

12. Address valid prior to or coincident with \overline{CE}_1 transition LOW and CE₂ transition HIGH.
13. Data I/O is high impedance if OE = V_{IH}.
14. If \overline{CE}_1 goes HIGH or CE₂ goes LOW simultaneously with WE HIGH, the output remains in a high-impedance state.

Switching Waveforms (continued)

Write Cycle No. 2 (\overline{WE} Controlled, \overline{OE} HIGH During Write)^[13,14]


62128V-11

Note:

15. During this period, the I/Os are in output state and input signals should not be applied.

Truth Table

\overline{CE}_1	\overline{CE}_2	\overline{OE}	\overline{WE}	I/O ₀ -I/O ₇	Mode	Power
H	X	X	X	High Z	Power-Down	Standby (I_{SB})
X	L	X	X	High Z	Power-Down	Standby (I_{SB})
L	H	L	H	Data Out	Read	Active (I_{CC})
L	H	X	L	Data In	Write	Active (I_{CC})
L	H	H	H	High Z	Selected, Outputs Disabled	Active (I_{CC})



Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
70	CY62128VL-70SC	S34	32-Lead 450-Mil SOIC	Commercial
	CY62128VLL-70SC	S34		
	CY62128VL-70ZC	Z32	32-Lead TSOP Type 1	
	CY62128VLL-70ZC	Z32		
	CY62128VL-70ZAC	ZA32	32-Lead STSOP Type 1	
	CY62128VLL-70ZAC	ZA32		
	CY62128VL-70ZRC	ZR32	32-Lead Reverse TSOP 1	
	CY62128VLL-70ZRC	ZR32		
70	CY62128VL-70SI	S34	32-Lead 450-Mil SOIC	Industrial
	CY62128VLL-70SI	S34		
	CY62128VL-70ZI	Z32	32-Lead TSOP Type 1	
	CY62128VLL-70ZI	Z32		
	CY62128VL-70ZAI	ZA32	32-Lead STSOP Type 1	
	CY62128VLL-70ZAI	ZA32		
	CY62128VL-70ZRI	ZR32	32-Lead Reverse TSOP 1	
	CY62128VLL-70ZRI	ZR32		
100	CY62128V25L-100SC	S34	32-Lead 450-Mil SOIC	Commercial
	CY62128V25LL-100SC	S34		
	CY62128V25L-100ZC	Z32	32-Lead TSOP Type 1	
	CY62128V25LL-100ZC	Z32		
	CY62128V25L-100ZAC	ZA32	32-Lead STSOP Type 1	
	CY62128V25LL-100ZAC	ZA32		
	CY62128V25L-100ZRC	ZR32	32-Lead Reverse TSOP 1	
	CY62128V25LL-100ZRC	ZR32		
100	CY62128V25L-100SI	S34	32-Lead 450-Mil SOIC	Industrial
	CY62128V25LL-100SI	S34		
	CY62128V25L-100ZI	Z32	32-Lead TSOP Type 1	
	CY62128V25LL-100ZI	Z32		
	CY62128V25L-100ZAI	ZA32	32-Lead STSOP Type 1	
	CY62128V25LL-100ZAI	ZA32		
	CY62128V25L-100ZRI	ZR32	32-Lead Reverse TSOP 1	
	CY62128V25LL-100ZRI	ZR32		
200	CY62128V18L-200SC	S34	32-Lead 450-Mil SOIC	Commercial
	CY62128V18LL-200SC	S34		
	CY62128V18L-200ZC	Z32	32-Lead TSOP Type 1	
	CY62128V18LL-200ZC	Z32		
	CY62128V18L-200ZAC	ZA32	32-Lead STSOP Type 1	
	CY62128V18LL-200ZAC	ZA32		
	CY62128V18L-200ZRC	ZR32	32-Lead Reverse TSOP 1	
	CY62128V18LL-200ZRC	ZR32		



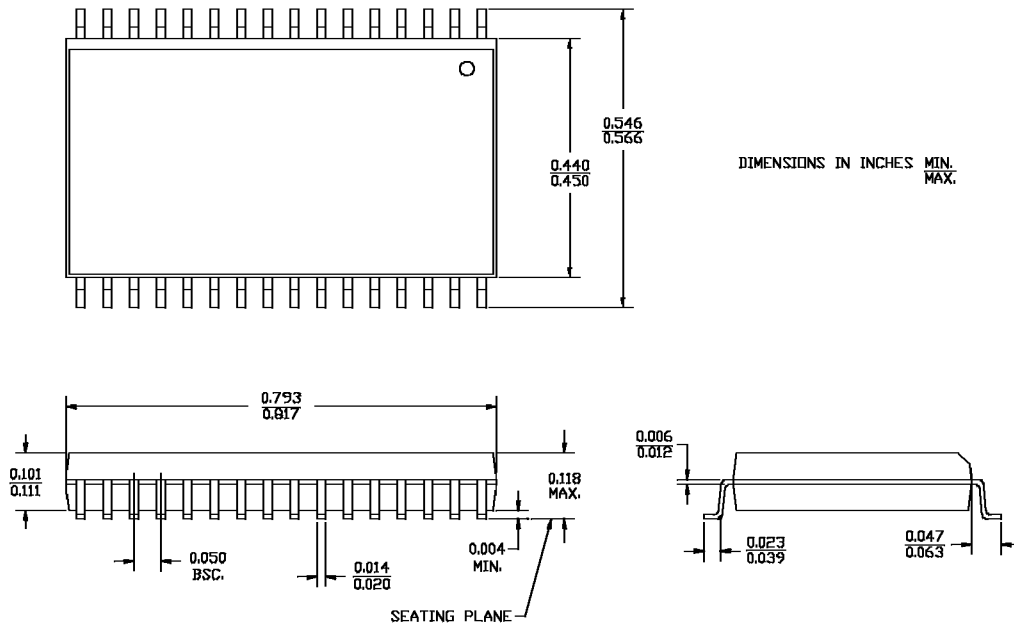
Ordering Information (continued)

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
200	CY62128V18L-200SI	S34	32-Lead 450-Mil SOIC	Industrial
	CY62128V18LL-200SI	S34		
	CY62128V18L-200ZI	Z32	32-Lead TSOP Type 1	
	CY62128V18LL-200ZI	Z32		
	CY62128V18L-200ZAI	ZA32	32-Lead STSOP Type 1	
	CY62128V18LL-200ZAI	ZA32		
	CY62128V18L-200ZRI	ZR32	32-Lead Reverse TSOP 1	
	CY62128V18LL-200ZRI	ZR32		

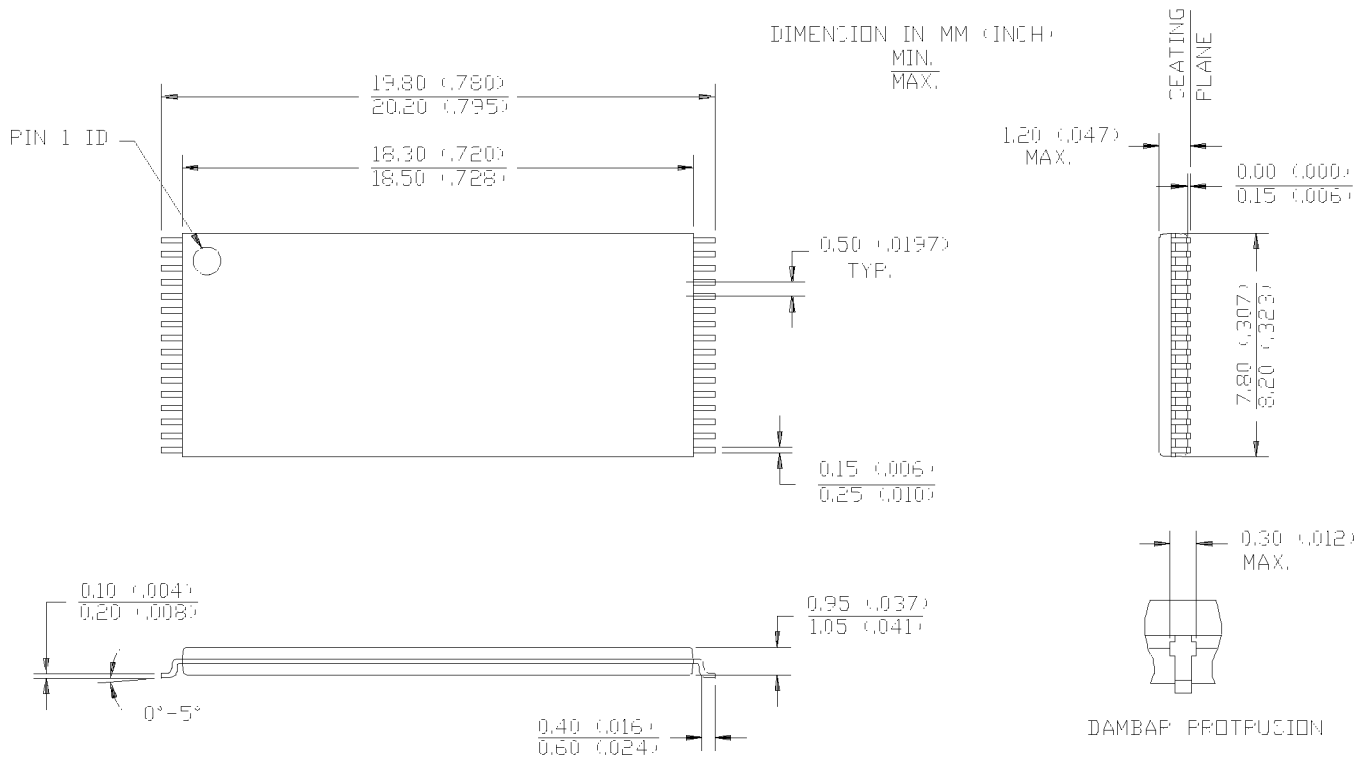
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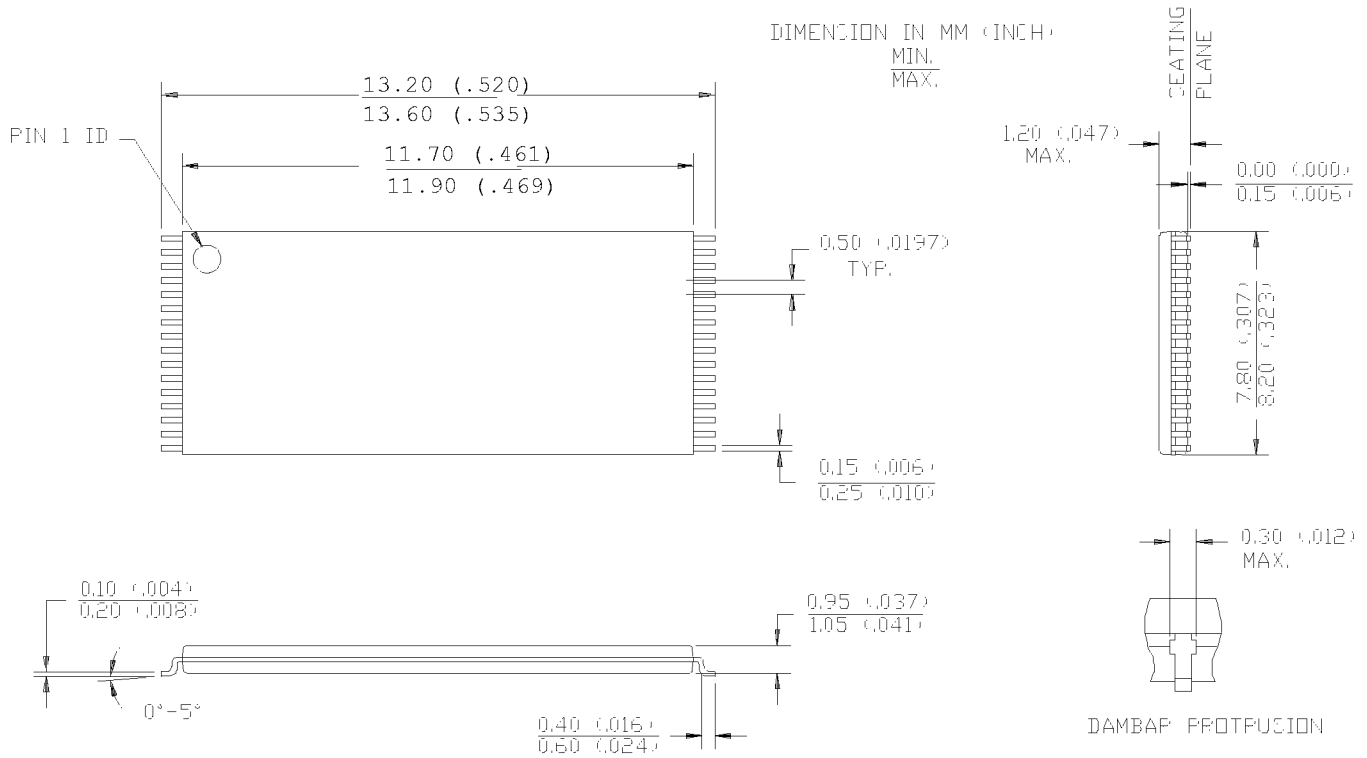
Package Diagrams

32-Lead (450 Mil) Molded SOIC S32



32-Lead Thin Small Outline Package Z32



Package Diagrams (continued)
32-Lead Shrunk Thin Small Outline Package ZA32

32-Lead Reverse Thin Small Outline Package ZR32
